

### **ABSTRACT OF THE DISCLOSURE**

**[0073]** Particles adherent to a semiconductor wafer surface, and defects such as SFs, mounds, and dislocations present near the semiconductor wafer surface can be accurately divided according to their types at a low cost without being influenced by an inspector's ability. The wafer is scanned with a laser beam, scattered or reflected light from the wafer surface is detected from multiple light optics having different detecting angles, respectively, and forms and types of the occurrences present on the wafer surface are determined based on a ratio of detected light intensities from the multiple light optics.

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